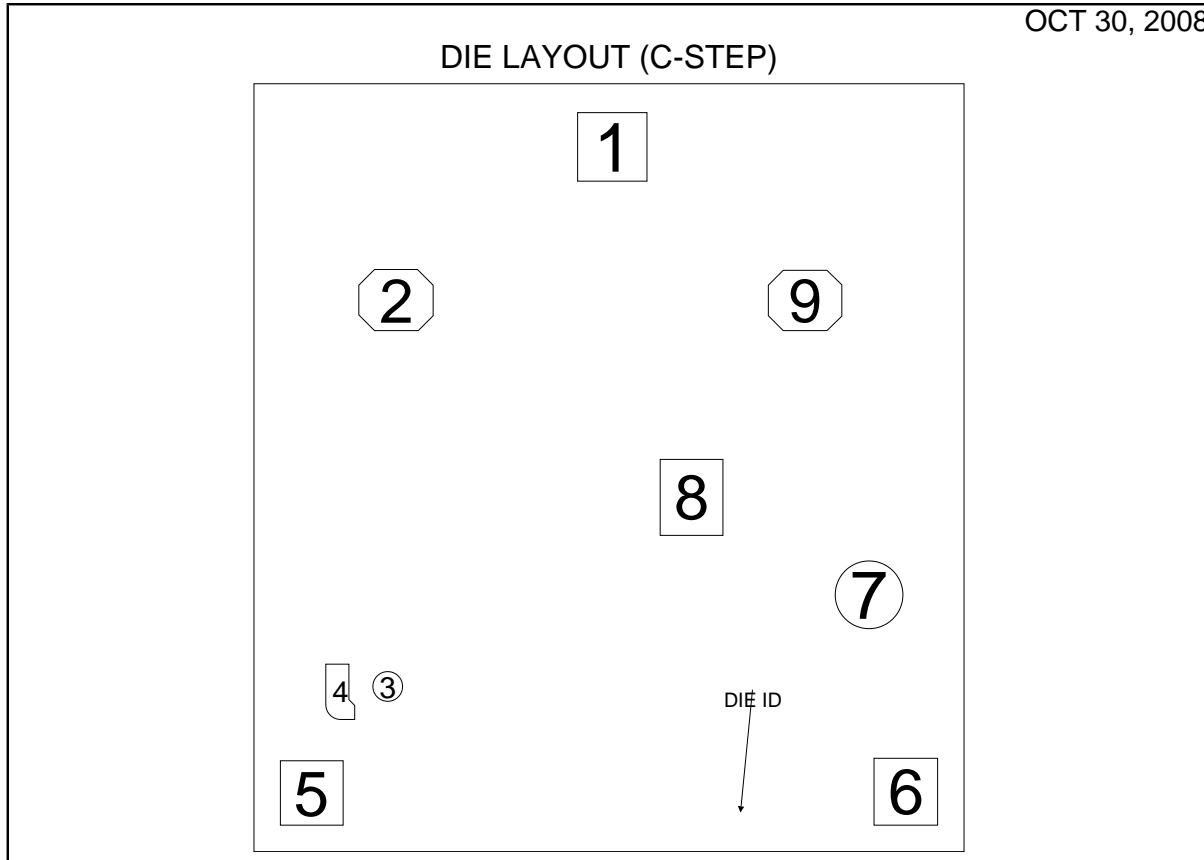


LM117H MDE MCD2250A
SMD#5962R9951705V9A
3-TERMINAL ADJUSTABLE REGULATOR

OCT 30, 2008



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	117C	Bond Pad Opening Size (min)	193.04µm x 198.12µm
Die Step	C	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	Gold
Die Size (Drawn)	2184.40µm x 2362.20µm 86.0mils x 93.0mils	Back Side Connection	Output
Thickness	254µm Nominal		
Min Pitch	1827.53µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(C-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
Input	1	10	987	213	x	211
Output	2	-655	516	229	x	188
NC	3	-681	-673	91	x	91
NC	4	-827	-690	89	x	170
Output	5	-914	-1001	193	x	198
Adj	6	913	-997	196	x	206
NC	7	800	-391	208	x	208
Input	8	254	-91	193	x	234
Output	9	603	514	226	x	185

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Notes

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